Description

This invention relates to a CCD imager in which a plurality of light receiving sections are formed for photoelectrical conversion on a semiconductor substrate and image signals are outputted from signals transferred from these light receiving sections. More particularly, it relates to a vertical overflow drain structure CCD imager in which electrical charges are swept off into the semiconductor substrate.

The CCD imager in general includes a number of light receiving sections arrayed in a two-dimensional matrix and signal charges for producing the image information are produced in these light receiving sections. As the structure of the light receiving section of this CCD imager, there is known a structure in which a P type well region is formed in an n type semiconductor substrate and in which a P type semiconductor surface region for suppressing the current otherwise generated on the surface of the light receiving section and an n^+ type semiconductor region forming a photodiode on the bottom side of the P type semiconductor surface region. The CCD imager of this structure is shown for example in the "Nikkei Micro-Devices", issue of October, 1987, p. 60 - 67, published by Nikkei McGraw Hill.

As the technique of sweeping off excess charges from the light receiving section, there is known a technique of providing a lateral overflow drain. The technique of sweeping off excess electron charges by specially designing the potential along the depth of the light receiving section, as disclosed in the Laid Open Japanese Patent Publication No. 18172/1986, is also known as the pertinent technique.

If the light receiving section has a pnpn structure, looking from its surface, it is necessary for the impurity concentration of the n type semiconductor substrate to be of the order of 1×10^{14} cm^{-3}, in order to provide for blooming margin and control at the three voltage level.

However, because of the reverse biased junction between the n type semiconductor substrate and the p type well region, the extent of the depletion layer is spread to about 30 μm for the aforementioned impurity concentration of the semiconductor substrate, such that the shuttering voltages is incresed to as high as 50 V in terms of the DC value. The result is the deteriorated reliability of the shuttering operation and the step-like regions produced on the monitor display surface on account of the infeasibility of the shuttering operation.

On the other hand, it is desirable that the amount of the stored charges be not increased at an illuminance corresponding to saturation. However, this has not been achieved satisfactorily in the above described light receiving section. Hence, a demand has been raised for improving knee characteristics.

Other attempts to control the blooming effect in vertical drain structures are disclosed in JP-A- 61 077 360 and EP-A- 0 265 271.

It is a principal object of the present invention to provide a CCD imager in which spreading of the depletion layer during shuttering may be suppressed to realize the low shuttering voltage.

It is another object of the present invention to provide a CCD imager in which the increase in the amount of the stored charges may be suppressed to improve the knee characteristics.

In the CCD imager according to claim 1, the light receiving section is of a structure in which the semiconductor regions of different conductivity types are formed alternately along the depth from the surface side of the section. In the embodiment according to claim 6, when the lowermost semiconductor region, such as, for example, the semiconductor substrate, is of the n type, the light receiving section has the pnpn structure when viewed from the surface side. This lowermost semiconductor region is formed by a semiconductor region of a low impurity concentration and a semiconductor region of a high impurity concentration which is provided on the bottom side of the low impurity concentration semiconductor region. A voltage is applied to the high impurity concentration semiconductor region for electronic shuttering. The depth of the high impurity concentration semiconductor region may be set so as to be within the domain of the depletion layer that is produced at the time of application of the shuttering voltage. By the lowermost high concentration semiconductor region of the dual structure substrate consisting of the low concentration semiconductor region and the high concentration semiconductor region, it becomes possible to lower the shuttering voltage and to improve knee characteristics.

Fig. 1 is a diagram showing the potential distribution along the depth of the light receiving section of the CCD image according to the present invention.

Fig. 2 is a diagrammatic cross-sectional view showing essential portions of an embodiment of a CCD imager according to the present invention.

Fig. 3 is a diagram showing changes in the shuttering voltage for an embodiment of the CCD imager according to the present invention as compared with those of a conventional CCD imager.

Fig. 4 is a diagram showing knee characteristics of an embodiment of the CCD imager according to the present invention as compared with those of a conventional CCD imager.

Referring first to Fig. 1, the operating principle of the CCD imager of the present invention will be explained.

In the CCD imager of the present invention, spreading of the depletion layer at the reversely biased junction between a semiconductor region of a second conductivity type and a low concentration semiconductor region

of a first conductivity type is suppressed by a high concentration semiconductor region of the first conductivity type to enable the charges to be discarded in the vertical direction at a lesser potential difference. The one-dimensional model of the potential is shown in Fig. 1.

In the one-dimensional model, shown in Fig. 1, the region from the surface to a depth x_{j1} is the p^+ type semiconductor surface region (N_A^+), while the region from the depth x_{j1} to a depth x_{j2} is the n^+ type first semiconductor region (N_D^+) and the region from the depth x_{j2} to a depth x_{j3} is the p type semiconductor region (N_A). The region from the depth x_{J3} to a depth W is the n type low concentration semiconductor region (N_D), while the region deeper than the depth W is the n^{++} type high concentration semiconductor region (N_D^{++}). The relation of the concentrations is given as $N_A^+ >> N_D^+$ and $N_D^{++} >> N_D$. It is assumed that the potential value at the bottom of the potential curve in the n^+ type first semiconductor region and the depth thereat are given by V_m and x_2, respectively, whilst the peak potential value in the p type semiconductor region and the depth thereat are given by V_B and x_3, respectively. It is also assumed that the substrate voltage V_{sub} is applied to the n^{++} type high concentration semiconductor region, whilst the p^+ type semiconductor surface region is fixed at the ground level.

From each boundary condition, the following equations,

$$x_{j2} - x_2 = \left[\frac{2\varepsilon_s N_A (V_M - V_B)}{qN_D^+(N_A + N_D^+)}\right]^{1/2} \quad \cdots\cdots\cdots \quad (1)$$

$$x_3 - x_{j2} = \left[\frac{2\varepsilon_s N_D^+ (V_M - V_B)}{qN_A (N_A + N_D^+)}\right]^{1/2} \quad \cdots\cdots\cdots \quad (2)$$

$$x_{j3} - x_3 = \left[\frac{2\varepsilon_s N_D (V_{sub} - V_B)}{qN_A (N_A + N_D)}\right]^{1/2} \quad \cdots\cdots\cdots \quad (3)$$

$$W - x_{j3} = \left[\frac{2\varepsilon_s N_A (V_{sub} - V_B)}{qN_D (N_A + N_D)}\right]^{1/2} \quad \cdots\cdots\cdots \quad (4)$$

$$V_M = \frac{qN_D^+}{2\varepsilon_s}(x_2 - x_{j1})^2 \quad (5)$$

are derived.

Also, from equation (5), the following equation (6)

$$x_2 = \left[\frac{2\varepsilon_s V_M}{qN_D^+}\right]^{1/2} + x_{j1} \quad \cdots\cdots\cdots \quad (6)$$

is derived.

Modifying the equation (4), the following equation (7)

$$V_B = V_{sub} - \frac{qN_D(N_A + N_D)}{2\varepsilon_s N_A} \cdot (W - x_{j3})^2 \quad (7)$$

is obtained.

Then, V_M is calculated. For simplicity, and λ, α are set to

$$\lambda = \left[\frac{qN_D^+}{2\varepsilon_s} \right]^{1/2},$$

$$\alpha = \frac{N_A}{N_A + N_D^+}$$

Substituting the equation (6) into the equation (1), the following equation (8)

$$\lambda (x_{j2} - x_{j1}) - \sqrt{V_M} = \sqrt{\alpha (V_M - V_B)} \quad (8)$$

is obtained. Solving this equation (8) as the quadratic equation for $\sqrt{V_M}$, the following equation (9)

$$\sqrt{V_M} = \frac{\lambda (x_{j2} - x_{j1})}{1 - \alpha} \cdot (1 + \sqrt{\beta}) \quad (9)$$

$$\left(\because \beta = \alpha \left[1 - \frac{(1 - \alpha) V_B}{\lambda^2 (x_{j2} - x_{j1})^2} \right] \right)$$

is obtained.

In this equation (9), in order for V_M to exist, the minus (-) sign of the double sign is to be adopted. Multiplying each side of the equation (9) by itself, the following equation (10)

$$V_M = \frac{\lambda^2 (x_{j2} - x_{j1})^2}{(1 - \alpha)^2} \cdot (1 - \sqrt{\beta})^2 \quad (10)$$

is derived.

Assuming that $V_M = V_B$ during application of the shuttering voltage, and modifying the equation (8),

$$V_B = \lambda^2 (x_{j2} - x_{j1})^2 \quad (11)]$$

Substituting this equation (11) into the equation (7),

$$V_{sub(shutter)} = \lambda^2 (x_{j2} - x_{j1})^2 + \frac{qN_D(N_A + N_D)}{2\varepsilon_s N_A} (W - x_{j3})^2 \quad (12)$$

It is seen from this equation (12) that the shuttering voltage V_{sub} (shutter) may be reduced by reducing the depth W of the high concentration semiconductor region.

As may be seen from equation (7), the value of the peak potential V_B in the p type semiconductor region becomes constant without dependency upon the amount of the stored charges. Hence, the knee characteristics may be improved, as in the case of the lateral overflow drain structure CCD imager.

For computing an exemplary shutter voltage V_{sub} (shutter), substituting $N_D^+ = 5 \times 10^{15} (cm^{-3})$, $N_A = 1 \times 10^{17} (cm^{-3})$, $x_{j3} = 3.5$ μm, $x_{j2} = 2.5$ μm, W=6 μm and $x_{j1} = 0.3$ μm, into the equation (12), we obtain

$$V_{sub}(shutter) \fallingdotseq 18(V).$$

In the above explanation, it is assumed that the depletion layer is compulsorily terminated at a depth W. At least, however, the tendency for the shutter voltage V_{sub}(shutter) to be reduced may be substantially realized by providing the high concentration semiconductor region of a first conductivity type within the domain of the depletion layer that is spread at the time of application of the shuttering voltage, thereby enabling electrical shuttering to be performed at a lower shutter voltage.

The CCD imager of the illustrative embodiment is an example of an interline transfer type CCD imager wherein the substrate is formed by an n type semiconductor region of a low impurity concentration and an n^{++} type region of a high impurity concentration to realize the lowering of the electrical shuttering voltage.

The structure of the CCD imager is shown in Fig. 2, wherein the n-type semiconductor substrate, which is the second semiconductor region of a first conductivity type, is comprised of an n type semiconductor region of a low impurity concentration 2 and an n^{++} type semiconductor substrate proper of a high impurity concentration 1. On the top of this n type semiconductor region of the lower impurity concentration 2 is formed a p type well region 3 which is a semiconductor region of the second conductivity type.

A light receiving section 6 is surrounded by this p type well region 3 and includes a p^+ type positive hole storage layer 5, which is a semiconductor surface region of the second conductivity type, and an n^+ type semiconductor region 4 on the bottom side of the positive hole storage layer 5. Thus the light receiving section 6 includes, looking from its surface, the p^+ type positive hole storage layer 5, n^+ type semiconductor region 4, p type well region 3, n type low concentration semiconductor region 2 and the n^{++} type high concentration sem-

iconductor substrate proper 1. By way of an example, the n type low concentration semiconductor region 2 has an impurity concentration of the order of 10^{14} cm^{-3}, whereas the n^{++} type high concentration semiconductor substrate proper 1 has the impurity concentration of the order of 10^{16} cm^{-3}, which is about 100 times that of the semiconductor region 2. The depth W of the interface between the n^{++} type high concentration semiconductor substrate 1 and the n type low concentration semiconductor region 2 is of the order of about 7 μm, whereas the depth x_{j3} of the junction between the p type well region 3 and the n type low concentration semiconductor region 2 is of the order of 3 μm. The substrate structure consisting of the low concentration semiconductor region and the high concentration semiconductor region is formed by ion implantation of n type high concentration impurities or p type compensatory impurities, or by stacking an n^+ type epitaxial layer on the n^{++} type high concentration semiconductor substrate proper 1.

In the p type well region 3, there are formed an n^+ type charge transfer section 11 at a distance from the n^+ type semiconductor region 4 along the surface of the region 3, and a second p type well 12 on the bottom side of the section 11. A read-out section 13 is defined in the domain between the n^+ type charge transfer section 11 and the n^+ type semiconductor region 4, and a channel is formed in this read-out section 13 by the electrical voltage in a polysilicon layer 15 which is stacked on the top of the well region 3 by the intermediary of an insulating layer 14. The light from an object to be imaged may fall on the light receiving section 6 which is devoid of the polysilicon layer 15 acting as the transfer electrode or an aluminum layer 16 acting as a light shield. Channel stop regions 17, 1 7 are formed on the lateral superficial sides of the n^+ type charge transfer section 11 and the light receiving section 6. In the interline CCD imager, the n^+ type charge transfer section 11 functions as a vertical register contiguous to a horizontal register provided orthogonally to the vertical register. The image signals transferred in the form of signal charges are taken out line by line from the horizontal register via output buffer.

The structure of the light receiving section is further explained in detail. A ground voltage V_{SS} is supplied to the p^+ type positive hole storage layer 5 on the surface of the p type well region 3, whilst a variable substrate voltage V_{sub} is supplied to the lowermost n^{++} type high concentration semiconductor substrate 1. The potential between the p^+ type positive hole storage region 5 and the n^{++} type high concentration semiconductor substrate proper 1 exhibits a curve such as is shown in Fig. 1, and a potential barrier V_B is formed in the p type well region 3, so that the signal charges continue to be stored at the bottom of the potential V_M of a region having a shallower depth than the potential barrier V_B. During electronic shuttering, a higher voltage is applied to the n^{++} type high concentration semiconductor substrate 1 to sweep off the signal charges into the substrate. In the CCD imager of the illustrative embodiment, spreading of the depletion layer at the junction between the p type well region 3 and the n type low concentration semiconductor region 2 is suppressed by the n^{++} type high concentration semiconductor substrate 1 to enable the shuttering to be performed at a lower electrical voltage.

The shuttering voltage characteristics are shown in Fig. 3, wherein the abscissa designates the substrate voltage V_{sub} and the ordinate designates the voltage ΔV_{sub} necessary to perform the shuttering. In the conventional pnpn type CCD imager, the voltage ΔV_{sub} is increased with increase in the substrate voltage V_{sub}, as indicated by a broken line B, so that sufficient shuttering cannot be achieved unless a high voltage is employed. In the pnpn n^{++} type CCD imager of the illustrative embodiment, a high voltage ΔV_{sub} is not required, even if the substrate voltage V_{sub} is increased, as indicated by a solid line A, so that the shuttering may be performed at a lower voltage.

As regards knee characteristics, in the conventional CCD imager, the amount of the stored charges is increased after the light volume exceeds the saturation value, as indicated by a broken line D in Fig. 4. In the CCD imager of the illustrative CCD imager, the increase in the stored charges may be suppressed, as indicated by a solid line C in Fig. 4, so that the blooming may be controlled effectively.

Claims

1. A CCD imager comprising:

a plurality of light receiving sections (6) each including a semiconductor surface region (5) of a second conductivity type; a first semiconductor region (4) of a first conductivity type, said first semiconductor region (4) storing signal charges; a second semiconductor region (3) of said second conductivity type, and a third semiconductor region (1, 2) of said first conductivity type, formed in this sequence, when seen from the surface along the depth thereof;

said third semiconductor region (1, 2) consisting of a low concentration semiconductor region (2) of said first conductivity type on the bottom side of said second semiconductor region (3) of said second conductivity type and a high concentration semiconductor region (1) of said first conductivity type on the

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iconductor substrate proper 1. By way of an example, the n type low concentration semiconductor region 2 has an impurity concentration of the order of 10^{14} cm^{-3}, whereas the n^{++} type high concentration semiconductor substrate proper 1 has the impurity concentration of the order of 10^{16} cm^{-3}, which is about 100 times that of the semiconductor region 2. The depth W of the interface between the n^{++} type high concentration semiconductor substrate 1 and the n type low concentration semiconductor region 2 is of the order of about 7 μm, whereas the depth x_{j3} of the junction between the p type well region 3 and the n type low concentration semiconductor region 2 is of the order of 3 μm. The substrate structure consisting of the low concentration semiconductor region and the high concentration semiconductor region is formed by ion implantation of n type high concentration impurities or p type compensatory impurities, or by stacking an n^+ type epitaxial layer on the n^{++} type high concentration semiconductor substrate proper 1.

In the p type well region 3, there are formed an n^+ type charge transfer section 11 at a distance from the n^+ type semiconductor region 4 along the surface of the region 3, and a second p type well 12 on the bottom side of the section 11. A read-out section 13 is defined in the domain between the n^+ type charge transfer section 11 and the n^+ type semiconductor region 4, and a channel is formed in this read-out section 13 by the electrical voltage in a polysilicon layer 15 which is stacked on the top of the well region 3 by the intermediary of an insulating layer 14. The light from an object to be imaged may fall on the light receiving section 6 which is devoid of the polysilicon layer 15 acting as the transfer electrode or an aluminum layer 16 acting as a light shield. Channel stop regions 17, 1 7 are formed on the lateral superficial sides of the n^+ type charge transfer section 11 and the light receiving section 6. In the interline CCD imager, the n^+ type charge transfer section 11 functions as a vertical register contiguous to a horizontal register provided orthogonally to the vertical register. The image signals transferred in the form of signal charges are taken out line by line from the horizontal register via output buffer.

The structure of the light receiving section is further explained in detail. A ground voltage V_{SS} is supplied to the p^+ type positive hole storage layer 5 on the surface of the p type well region 3, whilst a variable substrate voltage V_{sub} is supplied to the lowermost n^{++} type high concentration semiconductor substrate 1. The potential between the p^+ type positive hole storage region 5 and the n^{++} type high concentration semiconductor substrate proper 1 exhibits a curve such as is shown in Fig. 1, and a potential barrier V_B is formed in the p type well region 3, so that the signal charges continue to be stored at the bottom of the potential V_M of a region having a shallower depth than the potential barrier V_B. During electronic shuttering, a higher voltage is applied to the n^{++} type high concentration semiconductor substrate 1 to sweep off the signal charges into the substrate. In the CCD imager of the illustrative embodiment, spreading of the depletion layer at the junction between the p type well region 3 and the n type low concentration semiconductor region 2 is suppressed by the n^{++} type high concentration semiconductor substrate 1 to enable the shuttering to be performed at a lower electrical voltage.

The shuttering voltage characteristics are shown in Fig. 3, wherein the abscissa designates the substrate voltage V_{sub} and the ordinate designates the voltage ΔV_{sub} necessary to perform the shuttering. In the conventional pnpn type CCD imager, the voltage ΔV_{sub} is increased with increase in the substrate voltage V_{sub}, as indicated by a broken line B, so that sufficient shuttering cannot be achieved unless a high voltage is employed. In the pnpn n^{++} type CCD imager of the illustrative embodiment, a high voltage ΔV_{sub} is not required, even if the substrate voltage V_{sub} is increased, as indicated by a solid line A, so that the shuttering may be performed at a lower voltage.

As regards knee characteristics, in the conventional CCD imager, the amount of the stored charges is increased after the light volume exceeds the saturation value, as indicated by a broken line D in Fig. 4. In the CCD imager of the illustrative CCD imager, the increase in the stored charges may be suppressed, as indicated by a solid line C in Fig. 4, so that the blooming may be controlled effectively.

Claims

1. A CCD imager comprising:

a plurality of light receiving sections (6) each including a semiconductor surface region (5) of a second conductivity type; a first semiconductor region (4) of a first conductivity type, said first semiconductor region (4) storing signal charges; a second semiconductor region (3) of said second conductivity type, and a third semiconductor region (1, 2) of said first conductivity type, formed in this sequence, when seen from the surface along the depth thereof;

said third semiconductor region (1, 2) consisting of a low concentration semiconductor region (2) of said first conductivity type on the bottom side of said second semiconductor region (3) of said second conductivity type and a high concentration semiconductor region (1) of said first conductivity type on the

bottom side of said low concentration semiconductor region (2);
characterized in that said second semiconductor region (3) forms a potential barrier to said signal charges in said first semiconductor region (4).

2. The CCD imager according to claim 1, wherein said semiconductor surface region (5) of said second conductivity type is fixed at a ground potential, a variable voltage is applied to said second semiconductor region (4) of said first conductivity type and electrical charges are swept off into said second semiconductor region (1, 2).

3. The CCD imager according to claim 2, wherein said high concentration semiconductor region (1) of said first conductivity type is provided within the domain of a depletion layer of the junction between said semiconductor region (3) of said second conductivity type and the low concentration semiconductor region (2) of said first conductivity type at the time of application of a shuttering voltage.

4. The CCD imager according to anyone of claims 1 to 3, wherein the impurity concentration of said high concentration semiconductor region (1) is not less than 100 times the impurity concentration of said low concentration semiconductor region (2).

5. The CCD imager according to anyone of claims 1 to 4, wherein said light receiving sections (6) are arrayed in a two-dimensional matrix and charge transfer sections (11) are formed along vertical rows of said light receiving sections (6).

6. A CCD imager for outputting an image information comprising:
a plurality of light receiving sections (6) each including a p type semiconductor surface region (5), an n type first semiconductor region (4), said n type region (4) storing signal charges, a p type semiconductor region (3), said p type region (3) forming a potential barrier to said signal charges in said n type region (4) and an n type second semiconductor region (1, 2),
characterised in that
said second semiconductor region consisting of an n type low concentration semiconductor region (2) on the bottom side of said p type semiconductor region (3) and an n type high concentration semiconductor region (1) on the bottom side of said low concentration semiconductor region (2).

Patentansprüche

1. CCD-Bilderzeugungsvorrichtung, die in dieser Reihenfolge von der Oberfläche aus in die Tiefe betrachtet umfaßt:
mehrere Licht-Empfangsabschnitte (6), deren jeder ein Halbleiter-Oberflächengebiet (5) eines zweiten Leitfähigkeitstyps aufweist; ein erstes Halbleitergebiet (4) eines ersten Leitfähigkeitstyps, wobei das erste Halbleitergebiet (4) Signalladungen speichert; ein zweites Halbleitergebiet (3) des zweiten Leitfähigkeitstyps, und ein drittes Halbleitergebiet (1, 2) des ersten Leitfähigkeitstyps, wobei das dritte Halbleitergebiet (1, 2) aus einem nieder konzentrierten Halbleitergebiet (2) des ersten Leitfähigkeitstyps auf der unteren Seite des zweiten Halbleitergebiets (3) des zweiten Leitfähigkeitstyps und einem hoch konzentrierten Halbleitergebiet (1) des ersten Leitfähigkeitstyps auf der unteren Seite des nieder konzentrierten Halbleitergebiets (2) besteht,
dadurch gekennzeichnet, daß das zweite Halbleitergebiet (3) für die Signalladungen im ersten Halbleitergebiet (4) eine Potentialbarriere bildet.

2. CCD-Bilderzeugungsvorrichtung nach Anspruch 1, wobei das Halbleiter-Oberflächengebiet (5) des zweiten Leitfähigkeitstyps auf Erdpotential gehalten wird, eine variable Spannung an das zweite Halbleitergebiet (4) des ersten Leitfähigkeitstyps gelegt ist, und elektrische Ladungen in das zweite Halbleitergebiet (1, 2) gebracht werden.

3. CCD-Bilderzeugungsvorrichtung nach Anspruch 2, wobei das hoch konzentrierte Halbleitergebiet (1) des ersten Leitfähigkeitstyps innerhalb des Bereichs der Verarmungsschicht der Verbindung zwischen dem Halbleitergebiet (3) des zweiten Leitfähigkeitstyps und dem nieder konzentrierten Halbleitergebiet (2) des ersten Leitfähigkeitstyps zum Zeitpunkt der Anlegung einer Verschlußspannung vorgesehen ist.

4. CCD-Bilderzeugungsvorrichtung nach einem der Ansprüche 1 bis 3, wobei die Störstoffkonzentration des

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hoch konzentrierten Halbleitergebiets (1) mindestens das 100-fache der Störstoffkonzentration des nieder konzentrierten Halbleitergebiets (2) ist.

5. CCD-Bilderzeugungsvorrichtung nach einem der Ansprüche 1 bis 4, wobei die Licht-Empfangsabschnitte (6) in einer zweidimensionalen Matrix angeordnet sind, und wobei Ladungs-Übertragungsabschnitte (11) entlang vertikaler Reihen der Licht-Empfangsabschnitte (6) ausgebildet sind.

6. CCD-Bilderzeugungsvorrichtung zur Ausgabe einer Bildinformation, umfassend:
mehrere Licht-Empfangsabschnitte (6), deren jeder ein p-Typ Halbleiter-Oberflächengebiet (5), ein erstes n-Typ Halbleitergebiet (4), wobei das n-Typ Halbleitergebiet (4) Signalladungen speichert; ein p-Typ Halbleitergebiet (3), wobei das pTyp Gebiet (3) eine Potentialbarriere für die Signalladungen im n-Typ Gebiet (4) bildet, und ein zweites n-Typ Halbleitergebiet (1, 2) aufweist,
dadurch gekennzeichnet, daß
das zweite Halbleitergebiet aus einem n-Typ nieder konzentrierten Halbleitergebiet (2) auf der unteren Seite des p-Typ Halbleitergebiets (3) und einem n-Typ hoch konzentrierten Halbleitergebiet (1) auf der unteren Seite des nieder konzentrierten Halbleitergebiets (2) besteht.

Revendications

1. Dispositif de formation d'image CCD comportant:
une pluralité de parties réceptrices de lumière (6) comprenant chacune une région superficielle semiconductrice (5) d'un second type de conductivité ; une première région semiconductrice (4) d'un premier type de conductivité, ladite première région semiconductrice (4) stockant des charges de signal ; une seconde région semiconductrice (3) dudit second type de conductivité, et une troisième région semiconductrice (1, 2) dudit premier type de conductivité, formées dans cet ordre, en regardant depuis la surface le long de la profondeur de celui-ci ; ladite troisième région semiconductrice (1, 2) consistant en une région semiconductrice à faible concentration (2) dudit premier type de conductivité sur le côté inférieur de ladite seconde région semiconductrice (3) dudit second type de conductivité et une région semiconductrice à concentration élevée (1) dudit premier type de conductivité sur le côté inférieur de ladite région semiconductrice à faible concentration (2) ;
caractérisé en ce que ladite seconde région semiconductrice (3) forme une barrière de potentiel pour lesdites charges de signal dans ladite première région semiconductrice (4).

2. Dispositif de formation d'image CCD selon la revendication 1, dans lequel ladite région superficielle semiconductrice (5) dudit second type de conductivité est fixée à un potentiel de masse, une tension variable est appliquée à ladite seconde région semiconductrice (4) dudit premier type de conductivité et des charges électriques sont transférées dans ladite seconde région semiconductrice (1, 2).

3. Dispositif de formation d'image CCD selon la revendication 2, dans lequel ladite région semiconductrice à concentration élevée (1) dudit premier type de conductivité est prévue à l'intérieur du domaine d'une couche d'épuisement de la jonction entre ladite région semiconductrice (3) dudit second type de conductivité et la région semiconductrice à faible concentration (2) dudit premier type de conductivité à l'instant d'application d'une tension d'obturation.

4. Dispositif de formation d'image CCD selon l'une quelconque des revendications 1 à 3, dans lequel la concentration en impuretés de ladite région semiconductrice à concentration élevée (1) n'est pas inférieure à 100 fois la concentration en impuretés de ladite région semiconductrice à faible concentration (2).

5. Dispositif de formation d'image CCD selon l'une quelconque des revendications 1 à 4, dans lequel lesdites parties réceptrices de lumière (6) sont disposées selon une matrice bidimensionnelle et des parties de transfert de charge (11) sont formées le long de rangées verticales desdites parties réceptrices de lumière (6).

6. Dispositif de formation d'image CCD en vue de délivrer une information d'image comportant :
une pluralité de parties réceptrices de lumière (6) comprenant chacune une région superficielle semiconductrice de type p (5), une première région semiconductrice de type n (4), ladite région de type n (4) stockant des charges de signal, une région semiconductrice de type p (3), ladite région de type p

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(3) constituant une barrière de potentiel pour lesdites charges de signal dans ladite région de type n (4) et une seconde région semiconductrice de type n (1, 2),

caractérisé en ce que ladite seconde région semiconductrice consiste en une région semiconductrice à faible concentration de type n (2) sur le côté inférieur de ladite région semiconductrice de type p (3) et en une région semiconductrice à concentration élevée de type n (1) sur le côté inférieur de ladite région semiconductrice à faible concentration (2).